N-Channel UniFET MOSFET

200 V, 52 A, 49 m Ω

Description

UniFET MOSFET is ON Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

Features

- $R_{DS(on)} = 41 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10 \text{ V}, I_D = 26 \text{ A}$
- Low Gate Charge (Typ. 49 nC)
- Low C_{RSS} (Typ. 66 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

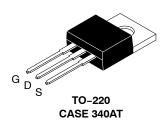
Applications

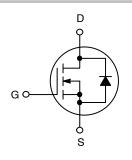
- PDP TV
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply



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ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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Symbol	Parameter		Value	Unit
V _{DSS}	Drain to Source Voltage		200	V
V _{GSS}	Gate to Source Voltage		±30	V
Ι _D	Drain Current	Continuous (T _C = 25°C)	52	А
		Continuous (T _C = 100°C)	33	
I _{DM}	Drain Current	Pulsed (Note 1)	208	А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		2520	mJ
I _{AR}	Avalanche Current (Note 1)		52	А
E _{AR}	Repetitive Avalanche Energy (Note 1)		35.7	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V/ns
P _D	Power Dissipation	(T _C = 25°C)	357	W
		Derate Above 25°C	2.86	W/°C
TJ, T _{STG}	Operating and Storage Temperature Range		–55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 1.4 mH, $I_{AS} = 52 \text{ A}$, $V_{DD} = 50 \text{ V}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 52 \text{ A}$, di/dt $\le 200 \text{ A/}\mu\text{s}$, $V_{DD} \le \text{BV}_{DSS}$, starting $T_J = 25^{\circ}\text{C}$. 4. Essentially independent of operating temperature typical characteristics.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.35	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number Top Marking		Package	Packing Method	Reel Size	Tape Width	Quantity	
FDP52N20	FDP52N20	TO-220	Tube	N/A	N/A	50 Units	

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS	-				-
BV _{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I_{D} = 250 $\mu A,~T_{J}$ = 25 $^{\circ}C$	200	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C	-	0.2	_	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 200 V, V_{GS} = 0 V	-	-	1	μΑ
		V_{DS} = 160 V, T_{C} = 125°C	-	-	10	
I _{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
ON CHARACTE	RISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \ \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 26 A	-	0.041	0.049	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 26 A	-	35	-	S
YNAMIC CHA	RACTERISTICS					
C _{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	-	2230	2900	pF
C _{oss}	Output Capacitance		_	540	700	pF
C _{rss}	Reverse Transfer Capacitance		-	66	100	pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 160 V, I _D = 52 A, V _{GS} = 10 V (Note 5)	-	49	63	nC
Q _{gs}	Gate to Source Gate Charge		-	19	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		_	24	-	nC
WITCHING CH	IARACTERISTICS	-				
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 100 \text{ V}, \text{ I}_{D} = 20 \text{ A},$	-	53	115	ns
t _r	Turn-On Rise Time	R _G = 25 Ω (Note 5)	-	175	359	ns
t _{d(off)}	Turn-Off Delay Time		-	48	107	ns
t _f	Turn-Off Fall Time		_	29	68	ns
RAIN-SOURC	E DIODE CHARACTERISTICS	•				
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	52	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	204	Α
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0 V, I _{SD} = 52 A	-	-	1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 52 A,$	-	162	-	ns
Qrr	Reverse Recovery Charge	dl _F /dt = 100 Å/μs	_	1.3	_	uC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.5. Essentially independent of operating temperature typical characteristics.

1.3

μC

Reverse Recovery Charge

 Q_{rr}

TYPICAL PERFORMANCE CHARACTERISTICS

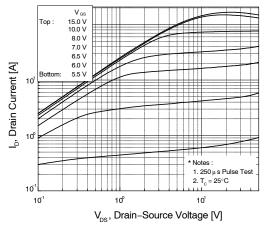


Figure 1. On-Region Characteristics

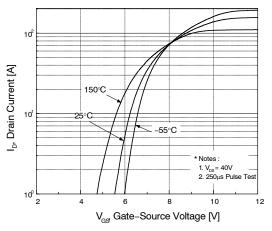


Figure 2. Transfer Characteristics

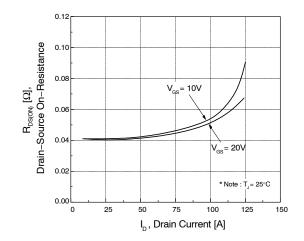


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

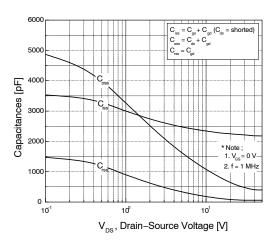


Figure 5. Capacitance Characteristics

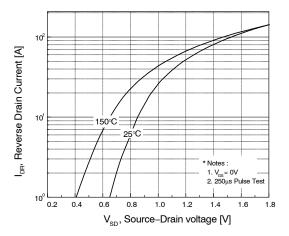


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

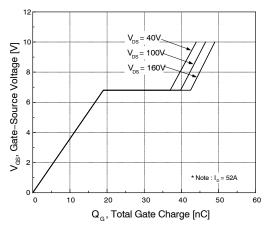


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS

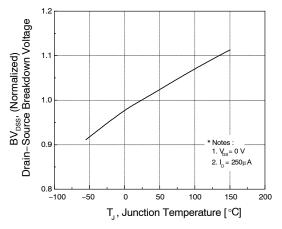


Figure 7. Breakdown Voltage Variation vs. Temperature

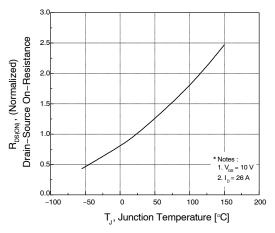


Figure 8. On-Resistance Variation vs. Temperature

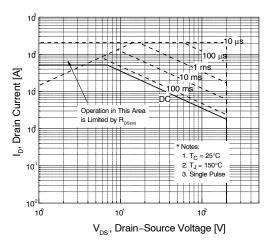


Figure 9. Maximum Safe Operation Area

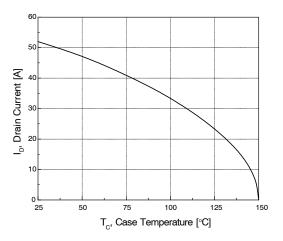


Figure 10. Maximum Drain Current

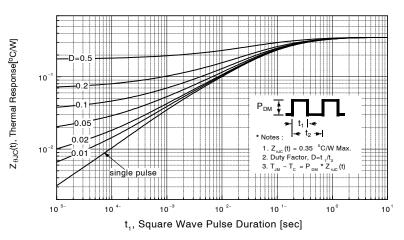


Figure 11. Transient Thermal Response Curve

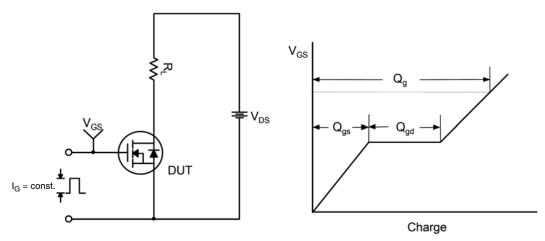


Figure 12. Gate Charge Test Circuit & Waveform

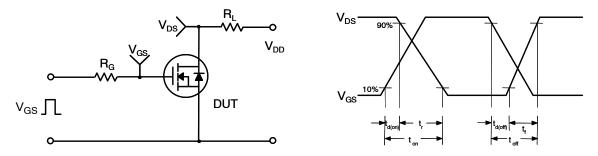


Figure 13. Resistive Switching Test Circuit & Waveforms

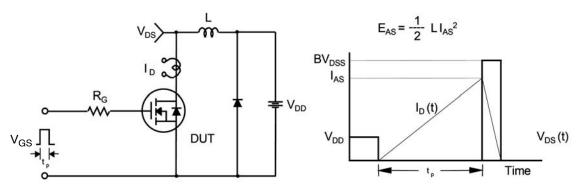
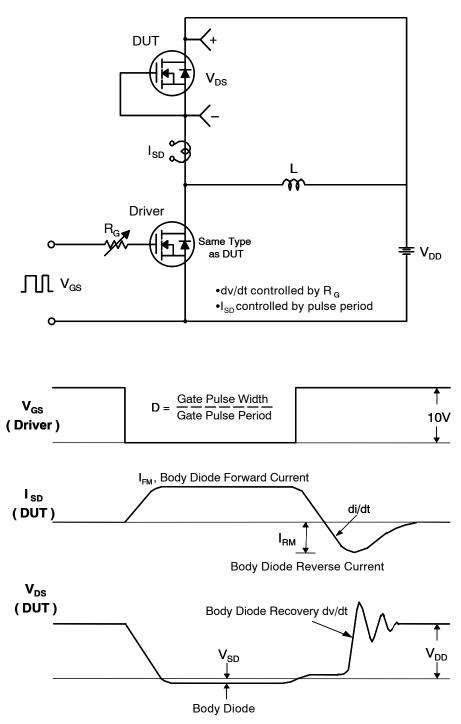
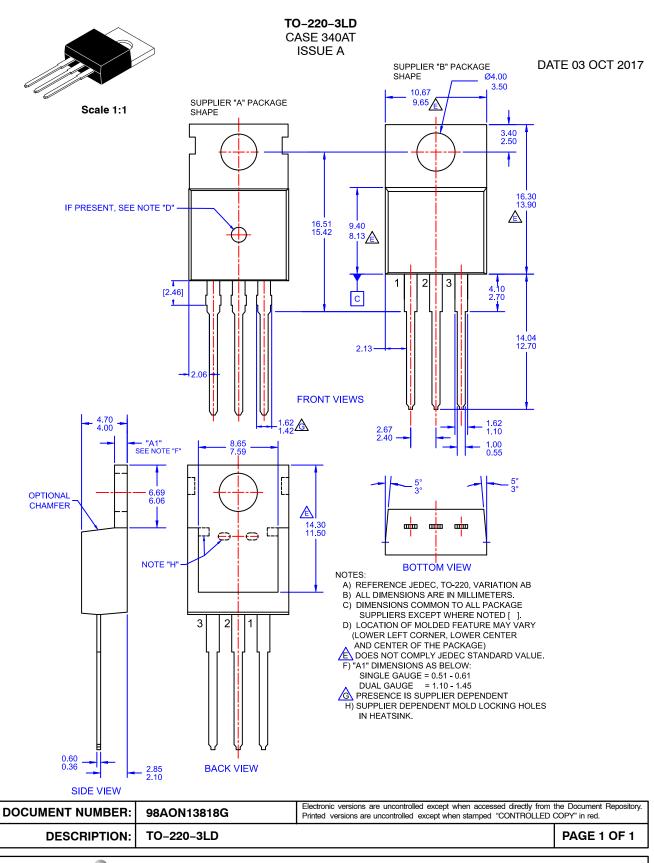


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms









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